

# FSA641 — 2:1 MIPI Switch, Featuring 2-Data and 1-Data Lane Configuration

### **Features**

Switch Type	2:1
Signal Types	MIPI, DPHY
Vcc	2.65 to 4.3 V
Input Signals	0 to V <sub>CC</sub>
R <sub>ON</sub>	7 Ω Typical HS MIPI
TON	10 Ω Typical LS MIPI
$\Delta R_{ON}$	0.75 Ω Typical HS & LS MIPI
Icc	1 μA Maximum
O <sub>IRR</sub>	-50 dB Typical
X <sub>TALK</sub>	-40 dB Typical
Bandwidth	1 GHz Typical
Channel-to-Channel Skew	15 ps Typical
Con	8 pF Typical
	20-Lead UMLP
Package	3.0x3.0x 0.55 mm, 0.4 mm
	Pitch
Ordering Information	FSA641UMX

# **Description**

The FSA641 is a 2:1 MIPI switch made for 2-data lane and 1-data lane modules. This part is configured as a single-pole, double-throw switch (SPDT) and is optimized for switching between two high-speed or low-power MIPI sources. The FSA641 has specially been designed for the MIPI specification and allows connection to either a CSI or DSI module. The FSA641 features an extremely low on capacitance ( $C_{ON}$ ) of 8 pF. The wide bandwidth (1 GHz) results in signals with minimum edge and phase distortion. Superior channel-to-channel crosstalk minimizes interference.

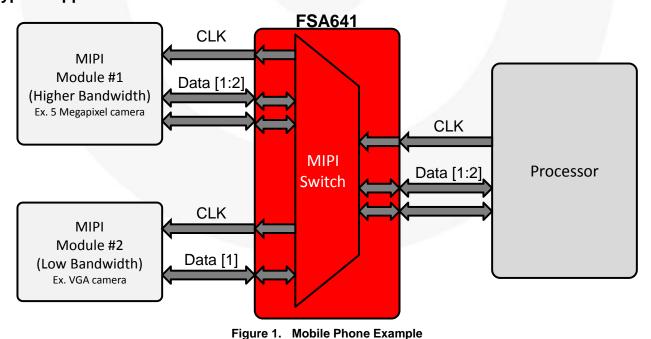
### **Related Resources**

- For samples and questions, please contact: Analog.Switch@fairchildsemi.com.
- FSA641 Demonstration Board

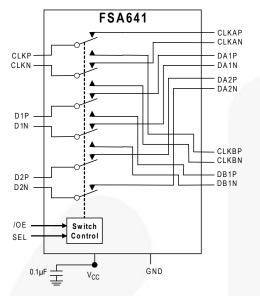
# **Applications**

- Cellular Phones, Smartphones
- Displays

# **Typical Application**



# **Pin Configuration**



CLKP CLKBN CLKBP DB1N DB1P

20 19 18 17 16

CLKAP

D1P 2 14 CLKAN

D1N 3 1 13 DA1P

D2P 4 1 12 DA1N

D2N 5 1 7 8 9 10

//OE GND VCC SEL DA2N

Figure 2. Functional Block Diagram

Figure 3. Pin Assignments (Top Through View)

# **Pin Descriptions**

Pin #	Pin Name	Туре	Description
20	CLKP	I/O	Common positive clock path
1	CLKN	I/O	Common negative clock path
2	D1P	I/O	Common positive data 1 path
3	D1N	I/O	Common negative data 1 path
4	D2P	I/O	Common positive data 2 path
5	D2N	I/O	Common negative data 2 path
15	CLKAP	I/O	A-port positive clock path
14	CLKAN	I/O	A-port negative clock path
13	DA1P	I/O	A-port positive data 1 path
12	DA1N	I/O	A-port negative data 1 path
11	DA2P	I/O	A-port positive data 2 path
10	DA2N	I/O	A-port negative data 2 path
18	CLKBP	I/O	B-port positive clock path
19	CLKBN	I/O	B-port negative clock path
16	DB1P	I/O	B-port positive data 1 path
17	DB1N	I/O	B-port negative data 1 path
6	/OE	Input	Output Enable (Active Low)
7	GND	Ground	Ground
8	VCC	Supply	Power; 0.1 µF decoupling capacitor to ground recommended
9	SEL	Input	A-port or B-port Select pin 0=A-port, 1= B-port
Paddle	n/a	NC	Not Connected

# **Truth Table**

SEL	/OE	Function
Don't Care	HIGH	Disconnect
LOW LOW D1, D2, CLK=DA1, DA2,		D1, D2, CLK=DA1, DA2, CLKA
HIGH	LOW	D1, CLK=DB1, CLKB; D2 OPEN

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Parameter			Unit
Vcc	Supply Voltage		-0.50	+5.25	V
$V_{CNTRL}$	DC Input Voltage (SEL, /OE) <sup>(1)</sup>		-0.5	V <sub>CC</sub>	V
V <sub>SW</sub>	DC Switch I/O Voltage <sup>(1)</sup>		-0.5	V <sub>CC</sub> + 0.3	V
I <sub>IK</sub>	DC Input Diode Current	DC Input Diode Current			mA
I <sub>OUT</sub>	DC Output Current		50	mA	
T <sub>STG</sub>	Storage Temperature		-65	+150	°C
		All Pins	1	6.5	
ESD	Human Body Model, JEDEC: JESD22-A114	I/O to GND		8.0	kV
ESD	7	Power to GND	(	16.0	κV
	Charged Device Model, JEDEC: JESD22-C101		1	2.0	

#### Note:

1. The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

# **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	2.65	4.30	V
V <sub>CNTRL</sub>	Control Input Voltage (SEL, /OE) <sup>(2)</sup>	0	$V_{CC}$	V
$V_{SW}$	Switch I/O Voltage	-0.5	$V_{CC}$	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C

### Note:

2. The control input must be held HIGH or LOW; it must not float.

### **DC Electrical Characteristics**

All typical values are T<sub>A</sub>=25°C unless otherwise specified.

Symbol	Parameter	Conditions	V <sub>cc</sub> (V)	T <sub>A</sub> =-40 to +85°C			Units
Symbol	ymbol Parameter Conditio		VCC (V)	Min.	Тур.	Max.	Units
V <sub>IK</sub>	Clamp Diode Voltage	I <sub>IN</sub> =-18 mA	2.775			-1.2	V
I <sub>IN</sub>	Control Input Leakage	$V_{SW}$ =0 to 4.3 V	4.3	-1		1	μA
V <sub>IH</sub>	Input Voltage High	V <sub>IN</sub> =0 to V <sub>CC</sub>	2.650 to 2.775	1.3			V
VIH	Imput voltage riigh		4.3	1.7			\ \
V <sub>IL</sub>	Input Voltage Low	$V_{IN}$ =0 to $V_{CC}$	2.650 to 2.775			0.5	V
loz	Off-State Leakage	A, B=0+0.3 V to $V_{CC}$ -0.3	4.3	-2		2	μA
I <sub>CC</sub>	Quiescent Supply Current	V <sub>CNTRL</sub> =0 or V <sub>CC</sub> , I <sub>OUT</sub> =0	4.3			1.0	μA
Ісст	Increase in I <sub>CC</sub> Current Per Control Voltage and V <sub>CC</sub>	V <sub>CNTRL</sub> =1.8 V	2.775			1.5	μA

# DC Electrical Characteristics, Low-Speed Mode

All typical values are T<sub>A</sub>=25°C unless otherwise specified.

Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	T <sub>A</sub> =-40 to +85°C			Units
Syllibol	Farameter	Conditions	VCC (V)	Min.	Тур.	Max.	Units
R <sub>ON</sub>	LS Switch On Resistance <sup>(3)</sup>	V <sub>SW</sub> =1.2 V, I <sub>ON</sub> =-10 mA, Figure 4	2.65		10	14	Ω
$\Delta R_{ON}$	LS Delta R <sub>ON</sub> <sup>(4)</sup>	V <sub>SW</sub> =1.2 V, I <sub>ON</sub> =-10 mA (Intra-pair)	2.65		0.75		Ω

### Notes:

- 3. Measured by the voltage drop between A/B and CLK/Dn pins at the indicated current through the switch.
- 4. Guaranteed by characterization.

# **DC Electrical Characteristics, High-Speed Mode**

All typical values are T<sub>A</sub>=25°C unless otherwise specified.

Symbol	Parameter	Conditions	V <sub>cc</sub> (V)	T <sub>A</sub> =-40 to +85°C			Units
Symbol	Conditions	ACC (A)	Min.	Тур.	Max.	Oilles	
R <sub>ON</sub>	HS Switch On Resistance <sup>(5)</sup>	V <sub>SW</sub> =0.4 V, I <sub>ON</sub> =-10 mA, Figure 4	2.65		7.0	9.5	Ω
$\Delta R_{ON}$	HS Delta R <sub>ON</sub> <sup>(6)</sup>	V <sub>SW</sub> =0.4 V, I <sub>ON</sub> =-10 mA (Intra-pair)	2.65		0.75	J	Ω

### Notes:

- 5. Measured by the voltage drop between A, B, and Dn pins at the indicated current through the switch.
- 6. Guaranteed by characterization.

### **AC Electrical Characteristics**

All values are at R<sub>L</sub>=50  $\Omega$  and R<sub>S</sub>=50  $\Omega$  and all typical values are V<sub>CC</sub>=2.775 V at T<sub>A</sub>=25°C unless otherwise specified.

Cumbal	Parameter	Conditions	V 00	T <sub>A</sub> =-4	10ºC to +	-85°C	Units
Symbol	Parameter	Conditions	V <sub>CC</sub> (V)	Min.	Тур.	Max.	Units
O <sub>IRR</sub>	Off Isolation <sup>(7)</sup>	f=100 MHz, $R_T$ =50 $\Omega$ Figure 14	2.775		-50		dB
Xtalk	Non-Adjacent Channel Crosstalk <sup>(7)</sup>	f=100 MHz, R <sub>T</sub> =50 Ω Figure 15	2.775		-40		dB
BW	-3db Bandwidth <sup>(7)</sup>	$C_L$ =0 pF, $R_T$ =50 $\Omega$ Figure 13	2.775		1.0		GHz
t <sub>ON</sub>	Turn-On Time SEL, /OE to Output	C <sub>L</sub> =5 pF, V <sub>SW</sub> =1.2 V Figure 6, Figure 7	2.650 to 2.775		20	37	ns
t <sub>OFF</sub>	Turn-Off Time SEL, /OE to Output	C <sub>L</sub> =5 pF, V <sub>SW</sub> =1.2 V Figure 6, Figure 7	2.650 to 2.775	3	15	27	ns
t <sub>PD</sub>	Propagation Delay <sup>(7)</sup>	C <sub>L</sub> =5 pF Figure 6, Figure 8	2.775		0.25		ns
t <sub>BBM</sub>	Break-Before-Make Time	C <sub>L</sub> =5 pF, V <sub>SW1</sub> =V <sub>SW2</sub> =1.2 V Figure 12	2.650 to 2.775	7	9	12	ns

### Note:

# **AC Electrical Characteristics, High-Speed**

All typical values are V<sub>CC</sub>=2.775V at T<sub>A</sub>=25°C unless otherwise specified.

Cumbal	Dovementor	Con ditions	T <sub>A</sub> =-40°C to +85°C		-85ºC	lle:te
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
t <sub>SK(Part_Part)</sub>	Channel-to-Channel Skew Across Multiple Parts <sup>(8,9)</sup>	TDR-Based Method (V <sub>SW</sub> -0.2V <sub>PP</sub> ,C <sub>L</sub> = C <sub>ON</sub> )		40	80	ps
tsk(Chl_Chl)	Channel-to-Channel Skew Within a Single Part <sup>(8)</sup>	TDR-Based Method (V <sub>SW</sub> -0.2V <sub>PP</sub> ,C <sub>L</sub> = C <sub>ON</sub> )	./	15	30	ps
t <sub>SK(Pulse)</sub>	Skew of Opposite Transitions in the Same Differential Channel <sup>(8)</sup>	TDR-Based Method (V <sub>SW</sub> -0.2V <sub>PP</sub> ,C <sub>L</sub> = C <sub>ON</sub> )		10	20	ps

### Notes:

- 8. Guaranteed by characterization.
- 9. Assumes the same V<sub>CC</sub> and temperature for all devices.

# Capacitance

Cumbal	Doromotor	Conditions	T <sub>A</sub> =-40°C to +85°C			Unito
Symbol	Symbol Parameter	Conditions	Min.	Тур.	Max.	Units
C <sub>IN</sub>	Control Pin Input Capacitance <sup>(10)</sup>	V <sub>CC</sub> =0 V		1.5		
Con	Dn/CLK- On Capacitance <sup>(10)</sup>	V <sub>CC</sub> =2.775 V, /OE=0V, f=1 MHz Figure 11		8.0		pF
C <sub>OFF</sub>	Dn/CLK Off Capacitance <sup>(9)</sup>	V <sub>CC</sub> =2.775 V, /OE=2.775 V, f=1 MHz Figure 10		2.5		

### Note:

10. Guaranteed by characterization.

<sup>7.</sup> Guaranteed by characterization.

# **Test Diagrams**

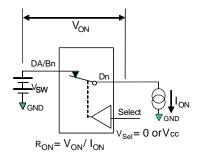
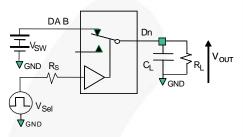


Figure 4. On Resistance



 $R_L$ ,  $R_S$ , an  $C_L$  ar fu ctions of th ap lication environment (se AC Tables for spe ific v lues)  $C_L$  inclu es test fixture an stra capacitance

Figure 6. AC Test Circuit Load

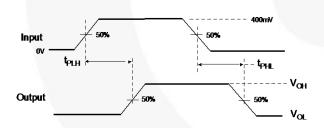


Figure 8. Propagation Delay  $(t_R t_F - 500 ps)$ 

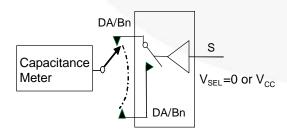
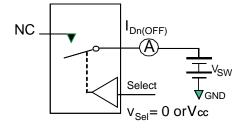


Figure 10. Channel Off Capacitance



\*\*Each switch port is tested separately

Figure 5. Off Leakage

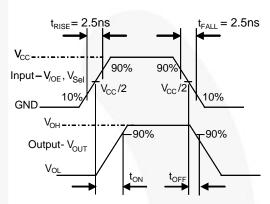


Figure 7. Turn-On / Turn-Off Waveforms

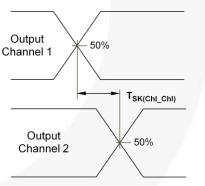


Figure 9. Channel-to-Channel Skew

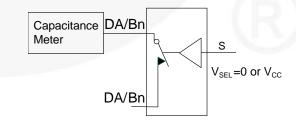


Figure 11. Channel On Capacitance

# **Test Diagrams** (Continued)

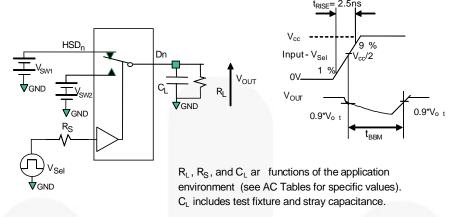


Figure 12. Break-Before-Make Interval Timing

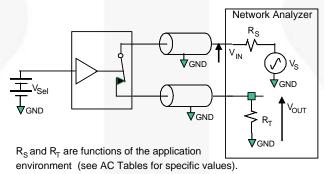
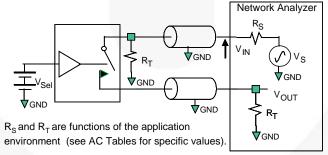
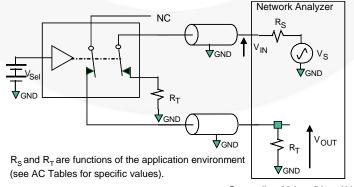


Figure 13. Bandwidth



Off isolation = 20 Log  $(V_{OUT} / V_{IN})$ 

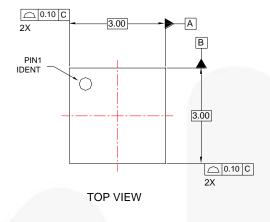
Figure 14. Channel Off Isolation

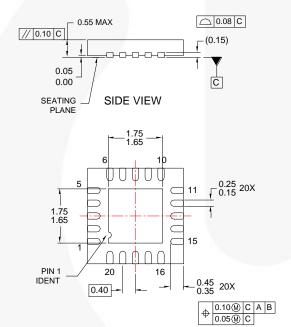


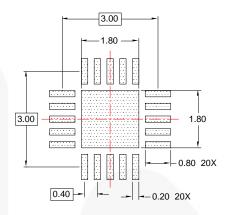
Crosstalk = 20 Log  $(V_{OUT} / V_{IN})$ 

Figure 15. Non-Adjacent Channel-to-Channel Crosstalk

# **Physical Dimensions**







### RECOMMENDED LAND PATTERN

### NOTES:

- A. PACKAGE CONFORMS TO JEDEC MO-248 VARIATION UEEE.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. LAND PATTERN RECOMMENDATION IS FROM PCB MATRIX CALCULATOR V2009.
- E. DRAWING FILENAME: MKT-UMLP20Brev1.

Figure 16. 20-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 3.0 x 3.0 mm

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings: <a href="http://www.fairchildsemi.com/dwg/UM/UMLP20B.pdf">http://www.fairchildsemi.com/dwg/UM/UMLP20B.pdf</a>.

**BOTTOM VIEW** 

For current tape and reel specifications, visit Fairchild Semiconductor's online packaging area: <a href="http://www.fairchildsemi.com/packaging/3.0x3.0">http://www.fairchildsemi.com/packaging/3.0x3.0</a> UMLP Pack TNR Spec.pdf.

# **Ordering Information**

Part	Top	Operating Temperature	Package
Number	Mark	Range	
FSA641UMX	F641	-40 to +85°C	20-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 3.0 x 3.0 mm





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### Definition of Terms

Definition of Terms		
Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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